



# GooLED-LG-6860 Pin Fin Heat Sink Φ68mm for LG Innotek

### **Features VS Benefits**

- \* The GooLED-LG-6860 LG Innotek Pin Fin LED Heat Sinks are specifically designed for luminaires using the LG Innotek LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 1,000 to 2,800 lumen.
- \* Thermal resistance range Rth 2.94°C/W.
- \* Modular design with mounting holes foreseen for direct mounting of LG Innotek COB series.
- \* Diameter 68.0mm standard height 60.0mm Other heights on request.
- \* Forged from highly conductive aluminum.

#### Zhaga LED engine and radiator assembly is a unified future international standardization

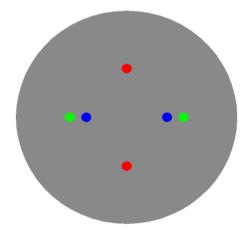
- \* Below you find an overview of LG Innotek COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.











# **LG Innotek LED Modules directly Mounting Options**

LG Innotek 7W&10W COB series.

LEMWM19480xxxxx; LEMWM19490xxxxxx;

With the Zhaga Book 3 holders for the green indicator marks.

TE Connectivity Holder: 2213382-1; Without the holders for the blue indicator marks.

Direct mounting with machine screws M3x6.5mm

#### LG Innotek 16W&21W COB series.

With the Zhaga Book 3 holders for the green indicator marks.

Without the holders for the red indicator marks.

Direct mounting with machine screws M3x6.5mm.

With the LEDiL products:







GooLED-LG-6860 Pin Fin Heat Sink Φ68mm for LG Innotek

# **Mounting Options and Drawings & Dimensions**

Example:GooLED-LG-6860-B-1,2

Example:GooLED-LG-68 1 - 2 - 3

1 Height (mm)

Anodising Color

B-Black

C-Clear

**Z-Custom** 

Mounting Options - see graphics for details Combinations available

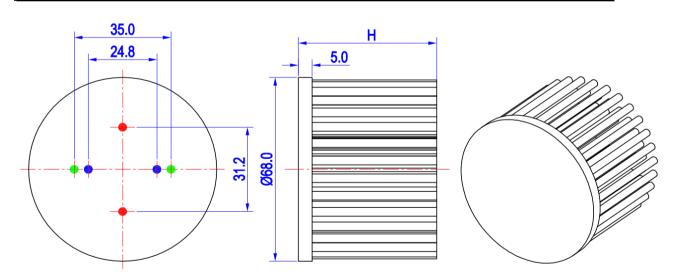
Ex.order code - 12

means option 1 and 2 combined

### Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
			Stella Series	Olivia series	INCAD	DEPTH	DISTANCE
1	7W&10W COB	/			МЗ	6.5mm	24.8mm/ 2-@180°
2		/			МЗ	6.5mm	31.2mm/ 2-@180°
3	16W&21W COB	BJB Holder 47.319.2011.50	/	FN14637-S; FN14828-M;	МЗ	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
		TE Holder 2213130-1					
	7W&10W COB	TE Holder 2213382-1					





## The product deta table

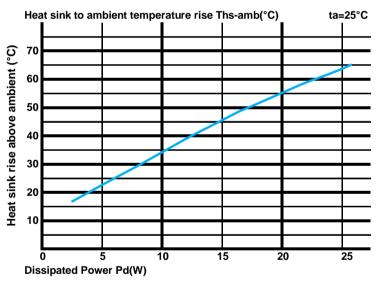


Model No.	GooLED-LG-6860		
Heatsink Size	Ф68хH60mm		
Heatsink Material	AL1070		
Finish	Black Anodized		
Weight (g)	176.0		
Dissipated power (Ths-amb,50℃)	17.0 (W)		
Cooling surface area (mm²)	70017		
Thermal Resistance (Rhs-amb)	2.94 (°C/W)		

### The thermal data table

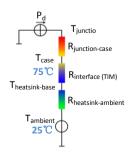
- \* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- \*To calculate the dissipated power please use the following formula:  $Pd = Pe \times (1-\eta L)$ .
  - Pd Dissipated power ; Pe Electrical power ;  $\eta L = \text{Light effciency of the LED module};$

		11		
Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		GooLED-LG-6860		
Dissipated Power Pd(W)	5.0	4.60	23.0	
	10.0	3.40	34.0	
	15.0	3.00	45.0	
	20.0	2.75	55.0	
	25.0	1.84	46.0	



- \*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:mingFarecommends} \mbox{ MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$

 $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.\ I-0.\ I\ 5mm\ is\ recommended.$ 



- \*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (Ths Ta)/Pd$
- $\theta\,$  Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- \*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{junction-case}$ , the thermal resistance of the TIM outside the package is  $R_{interface (TIM)}$  [°C/M], the thermal resistance with the heat sink is  $R_{heatsink-ambient}$  [°C/M], and the ambient temperature is  $T_{ambient}$  [°C].
- \*Thermal resistances outside the package  $R_{interface\,(TIM)}$  and  $R_{heatsink-ambient}$  can be integrated into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:

 $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$ 

